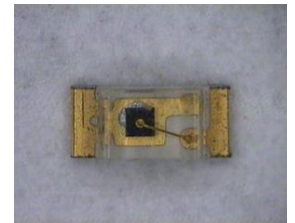


Technical Data Sheet 0603 Package Infrared LED EAIST1708A1

Features

- Peak wavelength $\lambda_p=940\text{nm}$
- Package in 8mm tape on 7" diameter reel
- Compatible with infrared and vapor phase reflow solder process.
- Pb free
- The product itself will remain within RoHS compliant versi



Description

- EAIST1708A1 is an infrared emitting diode in miniature SMD package which is molded in a water clear epoxy. The device is spectrally matched with silicon photodiode and phototransistor.

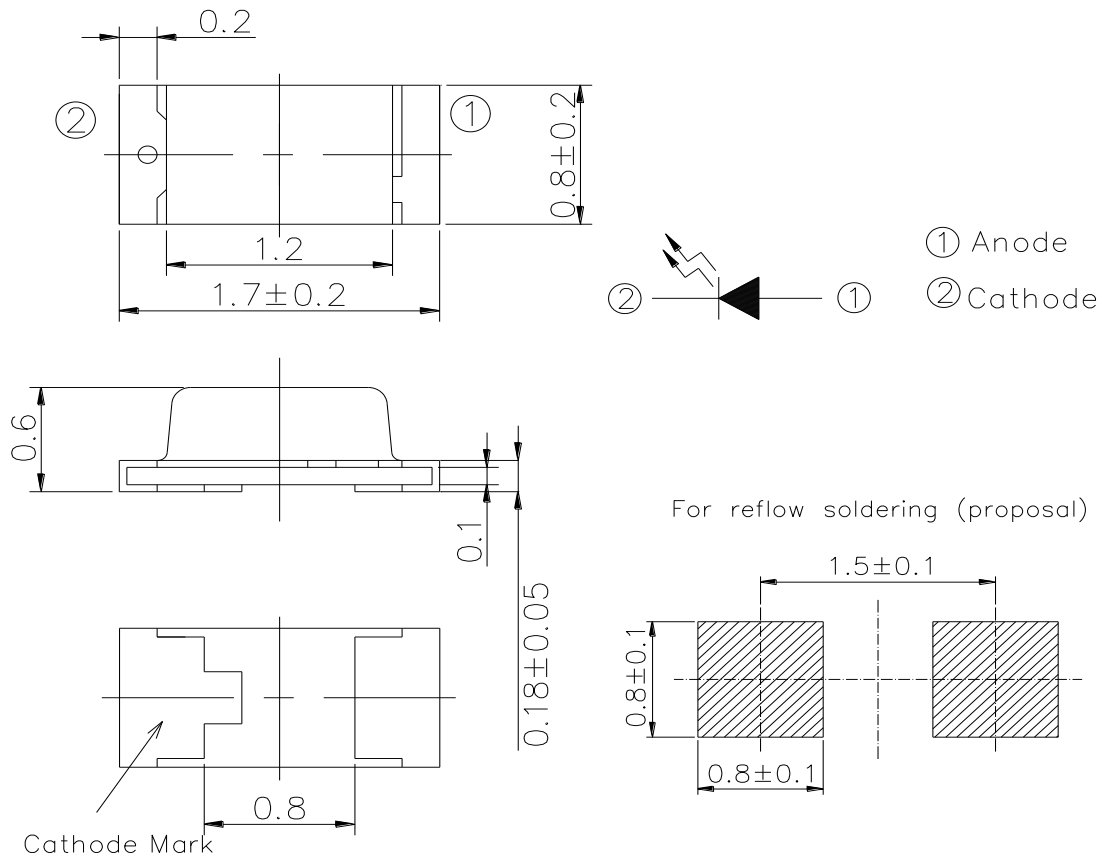
Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

Device Selection Guide

| Device No. | Chip Material | Lens Color |
|-------------|---------------|-------------|
| EAIST1708A1 | AlGaAs | Water clear |

Package Dimensions



- Notes:**
- 1.All dimensions are in millimeters
 - 2.Tolerances unless dimensions ±0.1mm

Absolute Maximum Ratings (Ta=25°C)

| Parameter | Symbol | Rating | Unit |
|---|------------------|------------|------|
| Continuous Forward Current | I _F | 65 | mA |
| Reverse Voltage | V _R | 5 | V |
| Operating Temperature | T _{opr} | -25 ~ +85 | °C |
| Storage Temperature | T _{stg} | -40 ~ +100 | °C |
| Soldering Temperature *1 | T _{sol} | 260 | °C |
| Power Dissipation at(or below) 25°C Free Air Temperature | P _d | 130 | mW |

Notes: *1:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|--------------------|-------------------|------|------|------|--------|--|
| Radiant Intensity | I _e | 0.2 | 0.6 | -- | mW /sr | I _F =20mA |
| | | -- | 4.0 | -- | | I _F =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1% |
| Peak Wavelength | λ _p | -- | 940 | -- | nm | I _F =20mA |
| Spectral Bandwidth | Δ λ | -- | 45 | -- | nm | I _F =20mA |
| Forward Voltage | V _F | -- | 1.2 | 1.5 | V | I _F =20mA |
| | | -- | 1.4 | 1.8 | | I _F =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1% |
| | | -- | 2.6 | 4.0 | | I _F =1A Pulse Width ≤ 100μ s ,Duty ≤ 1 |
| Reverse Current | I _R | -- | -- | 10 | μ A | V _R =5V |
| View Angle | 2θ _{1/2} | -- | 140 | -- | deg | I _F =20mA |

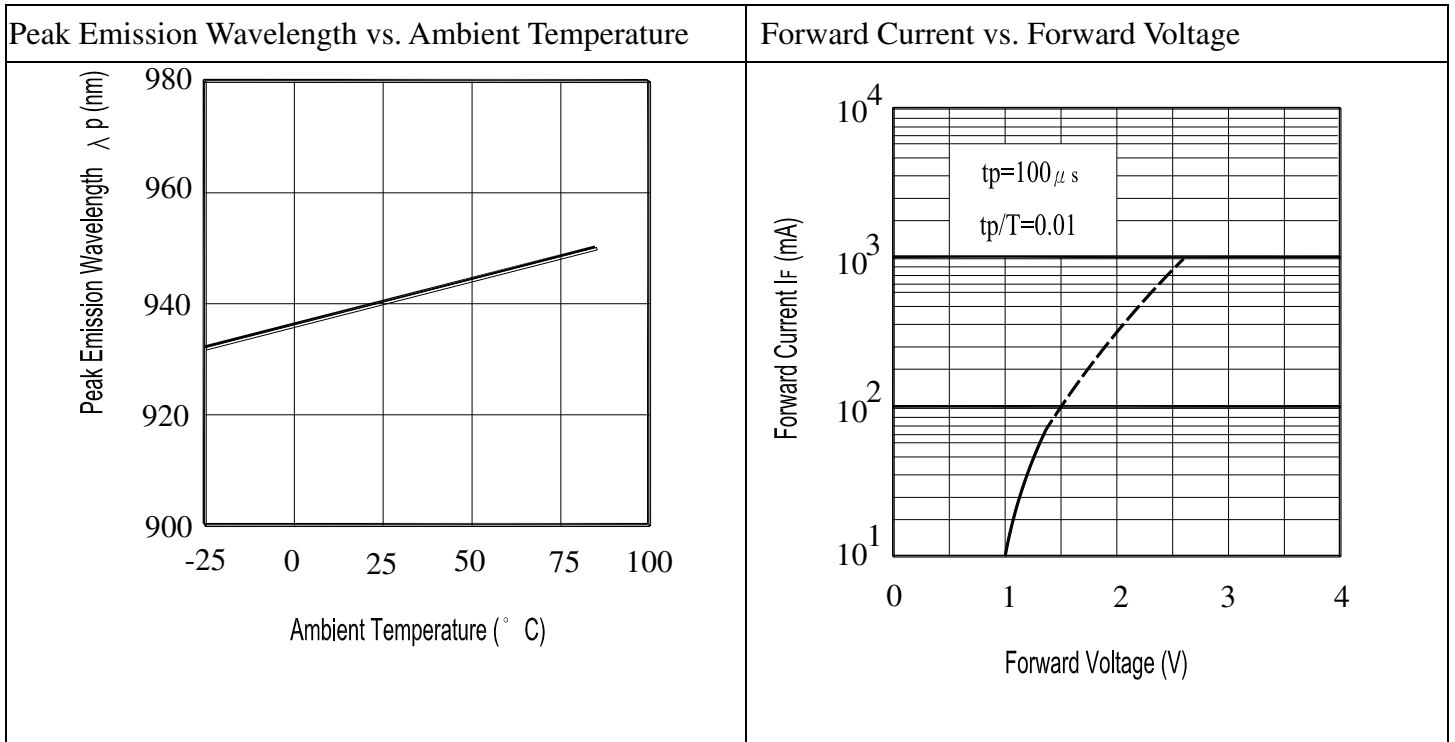
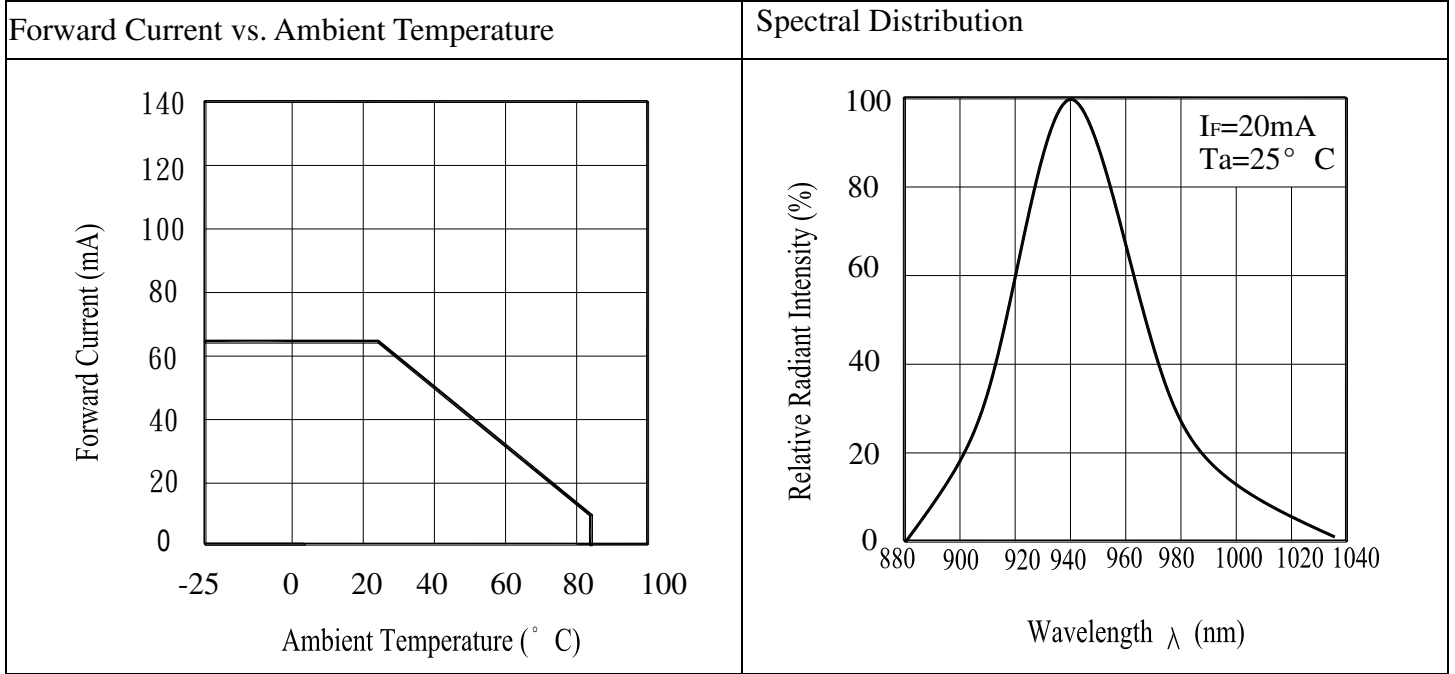
Rank

Condition : I_F=20mA

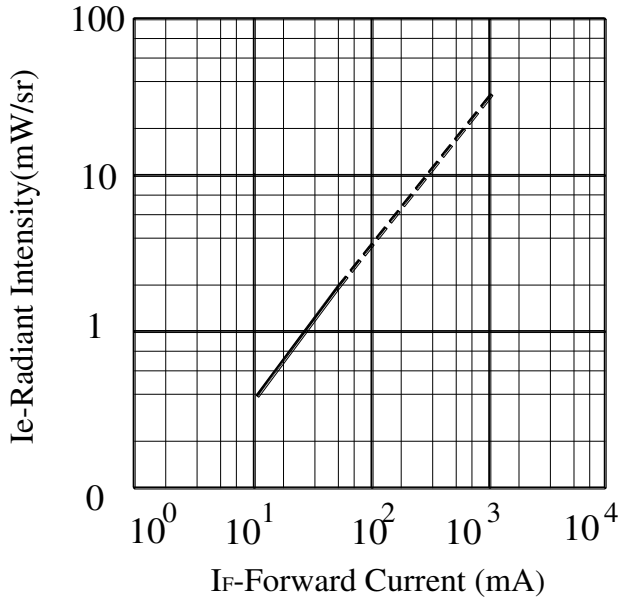
Unit : mW/sr

| Bin Number | E | F | G |
|------------|-----|-----|-----|
| Min | 0.2 | 0.5 | 1.0 |
| Max | 1.0 | 1.5 | 2.5 |

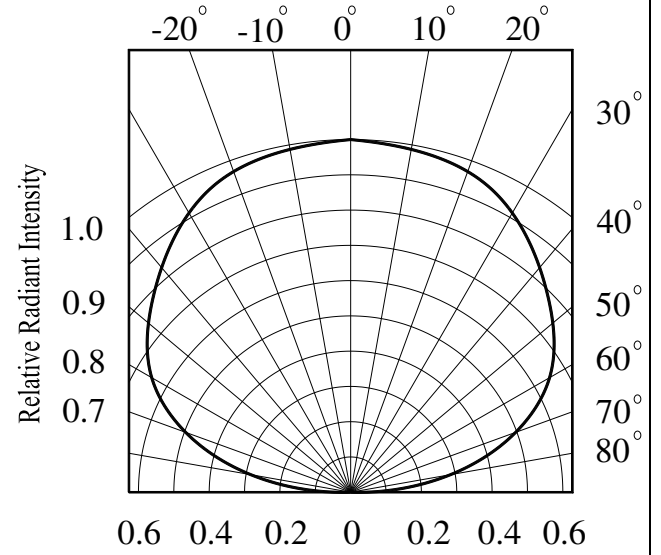
Typical Electrical/Optical/Characteristics Curves



Relative Intensity vs Forward Current



Relative Radiant Intensity vs. Angular Displacement



● **Precautions For Use**

1. Over-current-proof

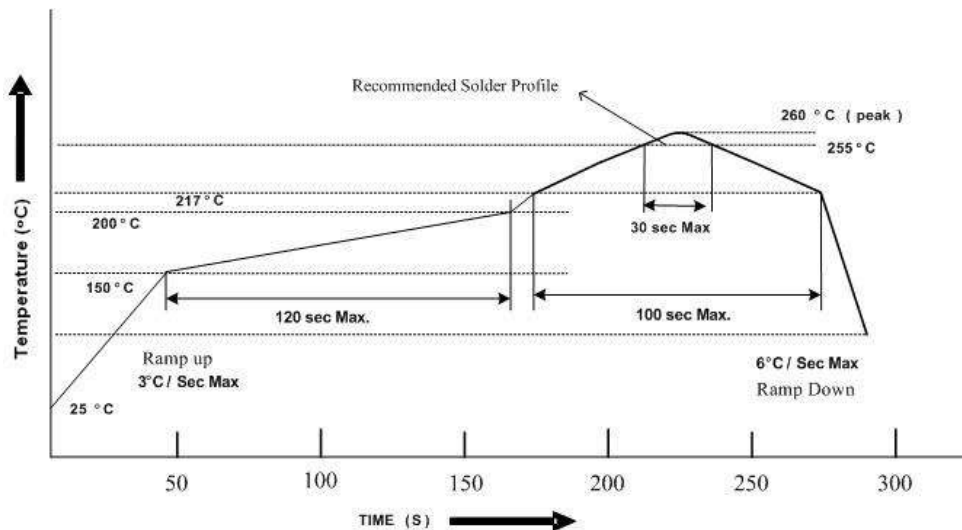
Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5°C for Min. 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



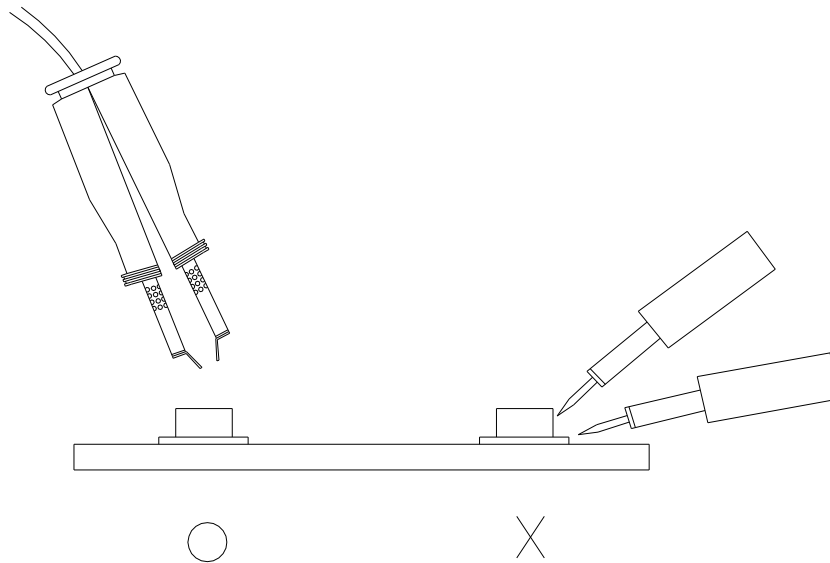
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

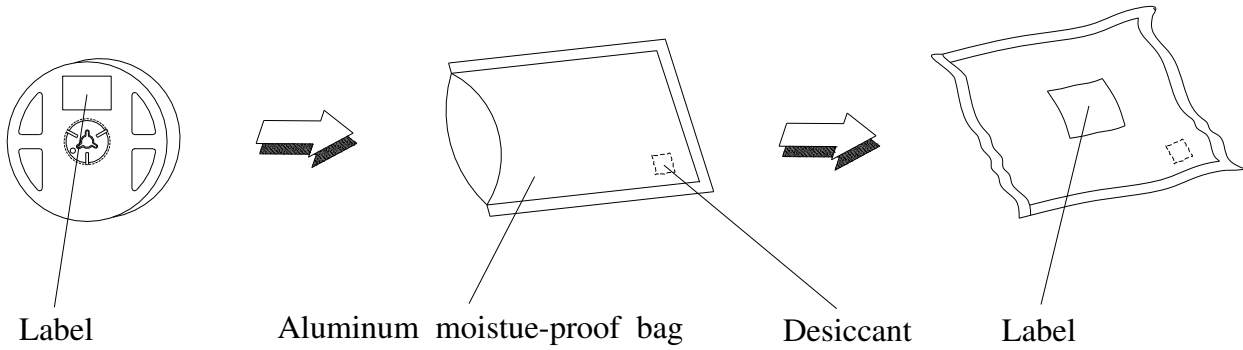
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Packing Procedure



Label Form Specification

| | | |
|------------------------------|--------------------------|-------------|
| | EVERLIGHT AMERICA | |
| CPN: XXXXXXXXXXXX | | |
| P/N: XXXXXXXXXXXX | | |
| | | RoHS |
| XXXXXXXXXXXXXXXXXXXX | | |
| QTY: XXXX | CAT: XXX | |
| | HUE: XXX | |
| | REF: XXX | |
| LOT NO: XXXXXXXXXXXXXXXXXXXX | | |
| | | |
| REFERENCE: XXXXXXXXXXXX | | |
| | | |
| MADE IN TAIWAN | | |

CPN: Customer's Production Number
P/N : Production Number
QTY: Packing Quantity
CAT: Ranks
HUE: Peak Wavelength
REF: Reference
LOT No: Lot Number
MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
3. These specification sheets include materials protected under copyright of Everlight Americas corporation. Please don't reproduce or cause anyone to reproduce them without Everlight Americas's consent.